

# SN5474, SN54LS74A, SN54S74 SN7474, SN74LS74A, SN74S74 DUAL D-TYPE POSITIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR

SDLS119 - DECEMBER 1983 - REVISED MARCH 1988

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

## description

These devices contain two independent D-type positive-edge-triggered flip-flops. A low level at the preset or clear inputs sets or resets the outputs regardless of the levels of the other inputs. When preset and clear are inactive (high), data at the D input meeting the setup time requirements are transferred to the outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold time interval, data at the D input may be changed without affecting the levels at the outputs.

The SN54' family is characterized for operation over the full military temperature range of -55°C to 125°C.

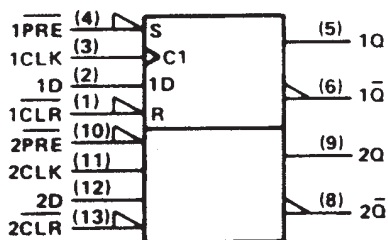
The SN74' family is characterized for operation from 0°C to 70°C.

FUNCTION TABLE

INPUTS				OUTPUTS	
PRE	CLR	CLK	D	Q	$\bar{Q}$
L	H	X	X	H	L
H	L	X	X	L	H
L	L	X	X	H <sup>†</sup>	H <sup>†</sup>
H	H	↑	H	H	L
H	H	↑	L	L	H
H	H	L	X	Q <sub>0</sub>	$\bar{Q}_0$

† The output levels in this configuration are not guaranteed to meet the minimum levels in  $V_{OH}$  if the lows at preset and clear are near  $V_{IL}$  maximum. Furthermore, this configuration is nonstable; that is, it will not persist when either preset or clear returns to its inactive (high) level.

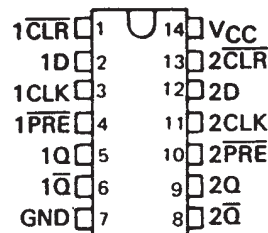
## logic symbol<sup>‡</sup>



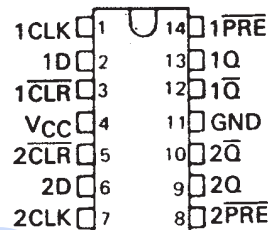
<sup>‡</sup>This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

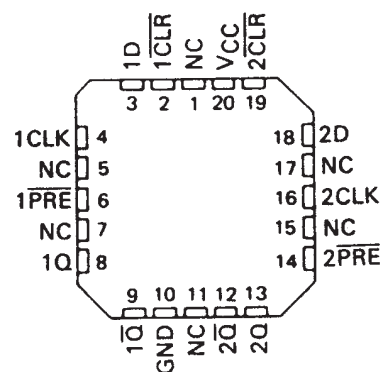
SN5474 . . . J PACKAGE  
SN54LS74A, SN54S74 . . . J OR W PACKAGE  
SN7474 . . . N PACKAGE  
SN74LS74A, SN74S74 . . . D OR N PACKAGE  
(TOP VIEW)



SN5474 . . . W PACKAGE  
(TOP VIEW)

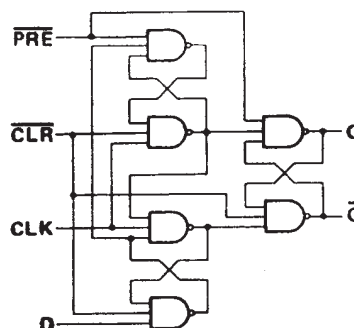


SN54LS74A, SN54S74 . . . FK PACKAGE  
(TOP VIEW)



NC - No internal connection

## logic diagram (positive logic)



PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

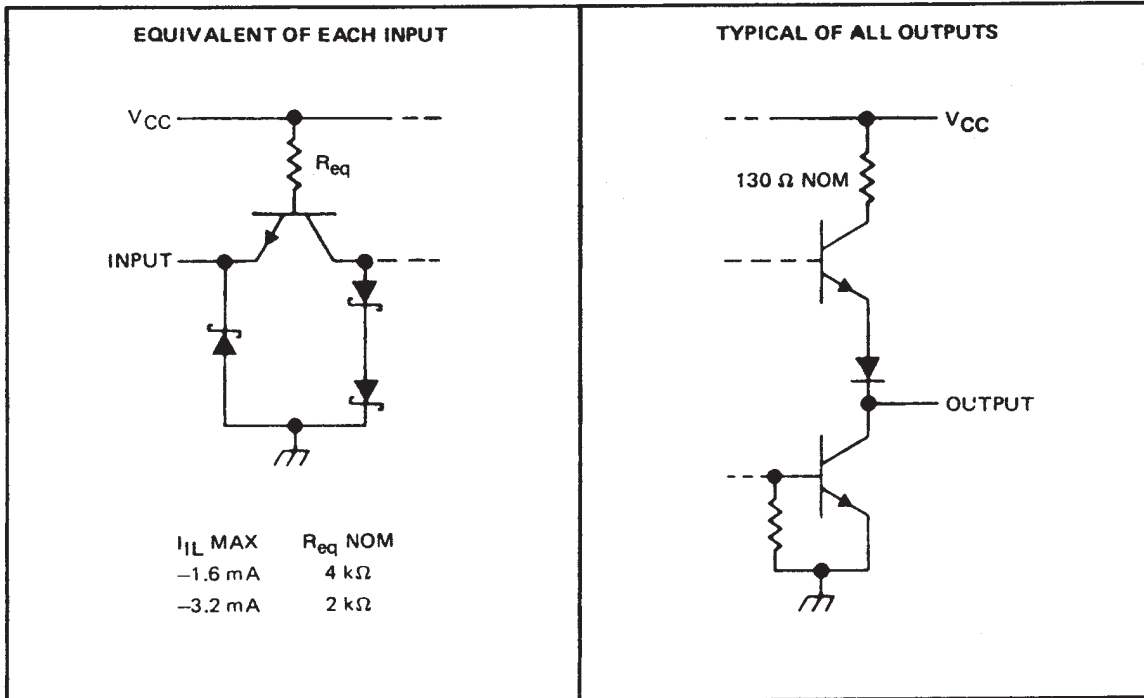
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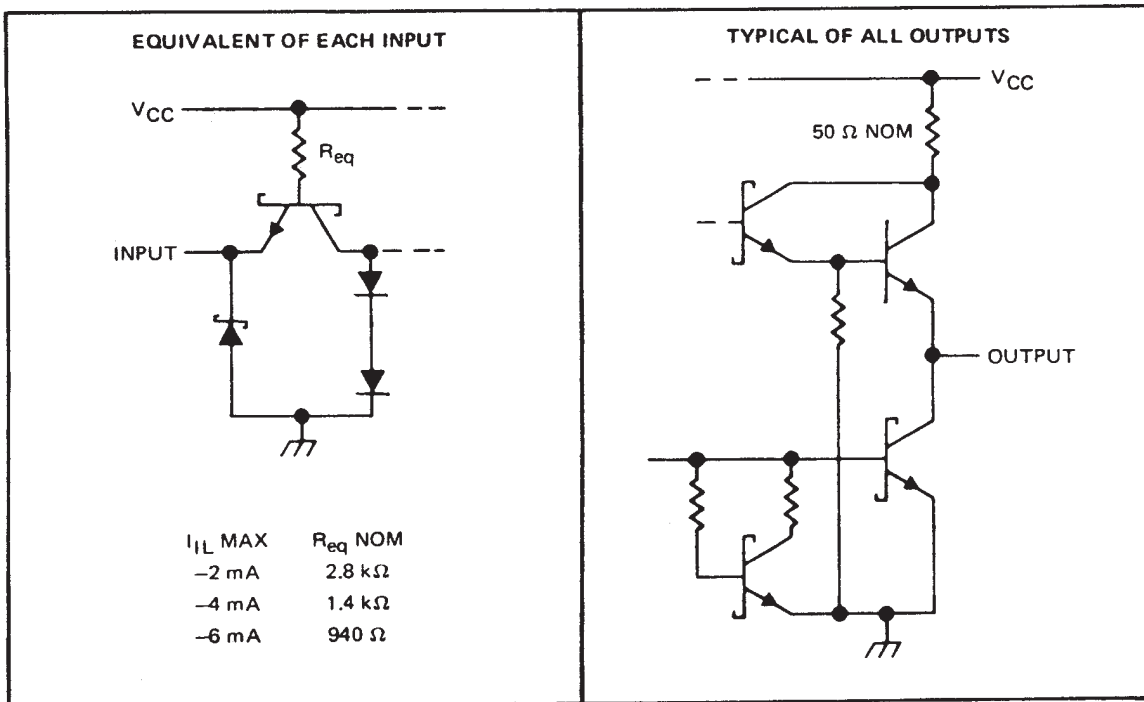
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schematics of inputs and outputs

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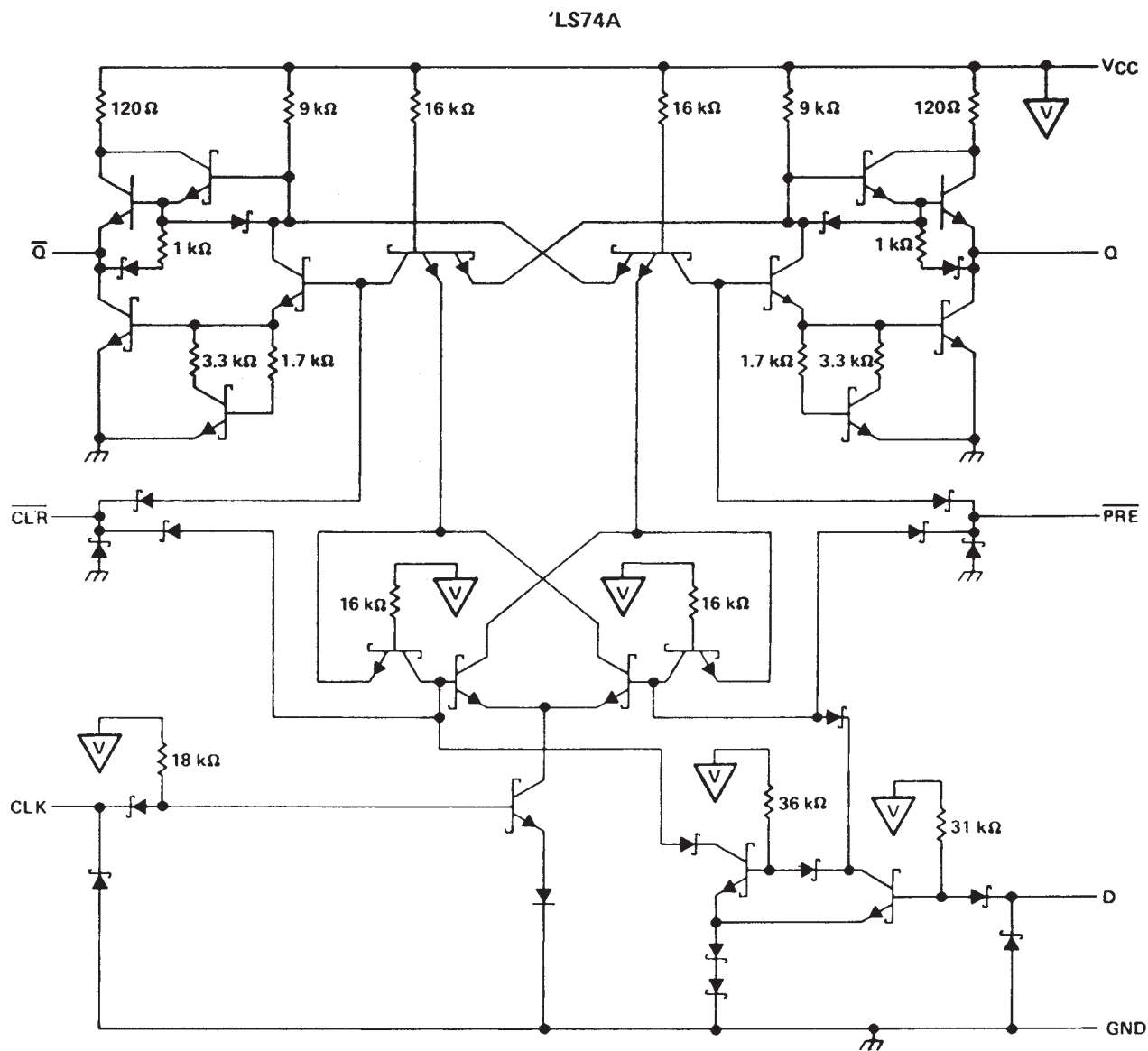
'S74



DUAL D-TYPE POSITIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR

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schematic



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, $V_{CC}$ (see Note 1) .....	7 V
Input voltage: '74, 'S74 .....	5.5 V
'LS74A .....	7 V
Operating free-air temperature range: SN54' .....	-55°C to 125°C
SN74' .....	0°C to 70°C
Storage temperature range .....	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.



**SN5474, SN54LS74A, SN54S74**

**SN7474, SN74LS74A, SN74S74**

**DUAL D-TYPE POSITIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR**

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**recommended operating conditions**

		SN5474			SN7474			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V <sub>CC</sub>	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V <sub>IH</sub>	High-level input voltage	2			2			V
V <sub>IL</sub>	Low-level input voltage			0.8			0.8	V
I <sub>OH</sub>	High-level output current			-0.4			-0.4	mA
I <sub>OL</sub>	Low-level output current			16			16	mA
t <sub>w</sub>	Pulse duration	CLK high		30	30		ns	
		CLK low		37	37			
		PRE or CLR low		30	30			
t <sub>su</sub>	Input setup time before CLK ↑	20			20			ns
t <sub>h</sub>	Input hold time-data after CLK ↑	5			5			ns
T <sub>A</sub>	Operating free-air temperature	-55		125	0		70	°C

**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER		TEST CONDITIONS†		SN5474		SN7474		UNIT
				MIN	TYP‡	MAX	MIN	
V <sub>IK</sub>		V <sub>CC</sub> = MIN,	I <sub>I</sub> = -12 mA	-1.5		-1.5		V
V <sub>OH</sub>		V <sub>CC</sub> = MIN,	V <sub>IH</sub> = 2 V, V <sub>IL</sub> = 0.8 V, I <sub>OH</sub> = -0.4 mA	2.4	3.4	2.4	3.4	V
V <sub>OL</sub>		V <sub>CC</sub> = MIN,	V <sub>IH</sub> = 2 V, V <sub>IL</sub> = 0.8 V, I <sub>OL</sub> = 16 mA	0.2	0.4	0.2	0.4	V
I <sub>I</sub>		V <sub>CC</sub> = MAX,	V <sub>I</sub> = 5.5 V	1		1		mA
I <sub>IH</sub>	D	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 2.4 V	40		40		μA
	CLR			120		120		
	All Other			80		80		
I <sub>IL</sub>	D	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 0.4 V	-1.6		-1.6		mA
	PRE‡			-1.6		-1.6		
	CLR‡			-3.2		-3.2		
	CLK			-3.2		-3.2		
I <sub>OS</sub> †		V <sub>CC</sub> = MAX		-20	-57	-18	-57	mA
I <sub>CC</sub> #		V <sub>CC</sub> = MAX,	See Note 2	8.5	15	8.5	15	mA

†For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.

§Clear is tested with preset high and preset is tested with clear high.

†Not more than one output should be shown at a time.

#Average per flip-flop.

NOTE 2: With all outputs open, I<sub>CC</sub> is measured with the Q and Q̄ outputs high in turn. At the time of measurement, the clock input is grounded.

**switching characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C (see note 3)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS		MIN	TYP	MAX	UNIT	
f <sub>max</sub>					15	25		MHz	
t <sub>PLH</sub>	PRE or CLR	Q or Q̄	R <sub>L</sub> = 400 Ω,	C <sub>L</sub> = 15 pF			25	ns	
t <sub>PHL</sub>							40	ns	
t <sub>PLH</sub>	CLK	Q or Q̄					14	25	ns
t <sub>PHL</sub>							20	40	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



DUAL D-TYPE POSITIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR

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recommended operating conditions

		SN54LS74A			SN74LS74A			UNIT	
		MIN	NOM	MAX	MIN	NOM	MAX		
V <sub>CC</sub>	Supply voltage	4.5	5	5.5	4.75	5	5.25	V	
V <sub>IH</sub>	High-level input voltage	2			2			V	
V <sub>IL</sub>	Low-level input voltage			0.7			0.8	V	
I <sub>OH</sub>	High-level output current			-0.4			-0.4	mA	
I <sub>OL</sub>	Low-level output current			4			8	mA	
f <sub>clock</sub>	Clock frequency	0		25	0		25	MHz	
t <sub>w</sub>	Pulse duration	CLK high		25	25			ns	
		PRE or CLR low		25	25				
t <sub>su</sub>	Setup time-before CLK ↑	High-level data		20	20			ns	
		Low-level data		20	20				
t <sub>h</sub>	Hold time-data after CLK ↑			5	5			ns	
T <sub>A</sub>	Operating free-air temperature			-55	125		0	70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN54LS74A			SN74LS74A			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V <sub>IK</sub>	V <sub>CC</sub> = MIN, I <sub>I</sub> = -18 mA	-1.5			-1.5			V
V <sub>OH</sub>	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, V <sub>IL</sub> = MAX, I <sub>OH</sub> = -0.4 mA	2.5	3.4		2.7	3.4		V
V <sub>OL</sub>	V <sub>CC</sub> = MIN, V <sub>IL</sub> = MAX, V <sub>IH</sub> = 2 V, I <sub>OL</sub> = 4 mA		0.25	0.4		0.25	0.4	V
	V <sub>CC</sub> = MIN, V <sub>IL</sub> = MAX, V <sub>IH</sub> = 2 V, I <sub>OL</sub> = 8 mA					0.35	0.5	
I <sub>I</sub>	D or CLK	0.1			0.1			mA
	CLR or PRE	0.2			0.2			
I <sub>IH</sub>	D or CLK	20			20			μA
	CLR or PRE	40			40			
I <sub>IL</sub>	D or CLK	-0.4			-0.4			mA
	CLR or PRE	-0.8			-0.8			
I <sub>OS</sub> §	V <sub>CC</sub> = MAX, See Note 4	-20		-100	-20		-100	mA
I <sub>CC</sub> (Total)	V <sub>CC</sub> = MAX, See Note 2	4		8	4		8	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.

§ Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

NOTE 2: With all outputs open, I<sub>CC</sub> is measured with the Q and Q̄ outputs high in turn. At the time of measurement, the clock input is grounded.

NOTE 4: For certain devices where state commutation can be caused by shorting an output to ground, an equivalent test may be performed with V<sub>O</sub> = 2.25 V and 2.125 V for the 54 family and the 74 family, respectively, with the minimum and maximum limits reduced to one half of their stated values.

switching characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS		MIN	TYP	MAX	UNIT
f <sub>max</sub>					25	33		MHz
t <sub>PLH</sub>	CLR, PRE or CLK	Q or Q̄	R <sub>L</sub> = 2 kΩ,	C <sub>L</sub> = 15 pF		13	25	ns
t <sub>PHL</sub>						25	40	ns

Note 3: Load circuits and voltage waveforms are shown in Section 1.



**SN5474, SN54LS74A, SN54S74**

**SN7474, SN74LS74A, SN74S74**

**DUAL D-TYPE POSITIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR**

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**recommended operating conditions**

		SN54S74			SN74S74			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V <sub>CC</sub>	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V <sub>IH</sub>	High-level input voltage	2			2			V
V <sub>IL</sub>	Low-level input voltage	0.8			0.8			V
I <sub>OH</sub>	High-level output current	-1			-1			mA
I <sub>OL</sub>	Low-level output current	20			20			mA
t <sub>w</sub>	Pulse duration	CLK high		6	6		ns	
		CLK low		7.3	7.3			
		CLR or PRE low		7	7			
t <sub>su</sub>	Setup time, before CLK ↑	High-level data		3	3		ns	
		Low-level data		3	3			
t <sub>h</sub>	Input hold time - data after CLK ↑	2			2			ns
T <sub>A</sub>	Operating free-air temperature	-55		125	0		70	°C

**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER		TEST CONDITIONS†	SN54S74			SN74S74			UNIT	
			MIN	TYP‡	MAX	MIN	TYP‡	MAX		
V <sub>IK</sub>		V <sub>CC</sub> = MIN, I <sub>I</sub> = -18 mA,			-1.2			-1.2	V	
V <sub>OH</sub>		V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, V <sub>IL</sub> = 0.8 V, I <sub>OH</sub> = -1 mA	2.5	3.4		2.7	3.4		V	
V <sub>OL</sub>		V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, V <sub>IL</sub> = 0.8 V, I <sub>OL</sub> = 20 mA			0.5			0.5	V	
I <sub>I</sub>		V <sub>CC</sub> = MAX, V <sub>I</sub> = 5.5 V			1			1	mA	
I <sub>IH</sub>	D	V <sub>CC</sub> = MAX, V <sub>I</sub> = 2.7 V			50			50	μA	
	CLR				150			150		
	PRE or CLK				100			100		
I <sub>IL</sub>	D	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.5 V			-2			-2	mA	
	CLR†				-6			-6		
	PRE†				-4			-4		
	CLK				-4			-4		
I <sub>OS</sub> ‡		V <sub>CC</sub> = MAX	-40		-100		-40		-100	mA
I <sub>CC</sub> #		V <sub>CC</sub> = MAX, See Note 2		15	25		15	25	mA	

†For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.

§Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

†Clear is tested with preset high and preset is tested with clear high.

#Average per flip-flop.

NOTE 2: With all outputs open, I<sub>CC</sub> is measured with the Q and Q̄ outputs high in turn. At the time of measurement, the clock input is grounded.

**switching characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C (see note 3)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f <sub>max</sub>			R <sub>L</sub> = 280 Ω, C <sub>L</sub> = 15 pF	75	110		MHz
t <sub>PLH</sub>	PRE or CLR	Q or Q̄			4	6	ns
t <sub>PHL</sub>	PRE or CLR (CLK high)	Q̄ or Q			9	13.5	ns
	PRE or CLR (CLK low)				5	8	
t <sub>PLH</sub>	CLK	Q or Q̄			6	9	ns
t <sub>PHL</sub>					6	9	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
JM38510/00205BCA	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
JM38510/00205BDA	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI
JM38510/00205BDA	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI
JM38510/07101BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/07101BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/07101BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/07101BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30102B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/30102B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/30102BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/30102BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/30102BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30102BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30102SCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/30102SCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/30102SDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30102SDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SN5474J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN5474J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN54LS74AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54LS74AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54S74J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54S74J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN7474DR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN7474DR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN7474N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7474N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7474N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7474N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS74AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ADBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ADBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ADBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ADBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ADBRG4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ADBRG4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
						no Sb/Br)		
SN74LS74ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74AJ	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74LS74AJ	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74LS74AN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS74AN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS74AN3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS74AN3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS74ANE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS74ANE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS74ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ANSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ANSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S74D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S74D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S74DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S74DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S74DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM



Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74S74DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S74N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S74N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S74N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74S74N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74S74NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S74NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S74NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S74NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S74NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S74NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S74NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S74NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ5474J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SNJ5474J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SNJ5474W	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI
SNJ5474W	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI
SNJ54LS74AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS74AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS74AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS74AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS74AW	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS74AW	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54S74FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54S74FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54S74J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54S74J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54S74W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54S74W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

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(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

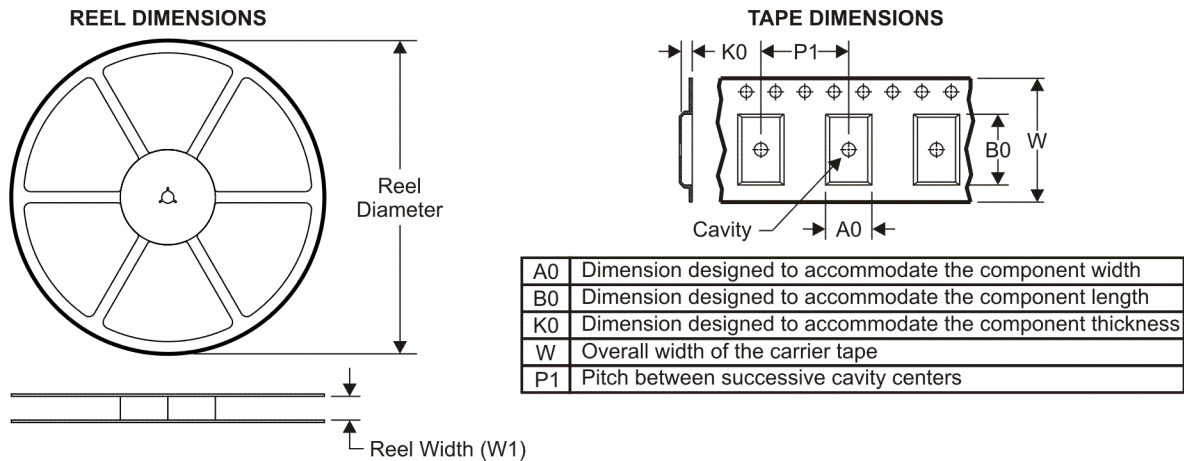
**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS74ADBR	SSOP	DB	14	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN74LS74ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS74ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74S74NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS74ADBR	SSOP	DB	14	2000	346.0	346.0	33.0
SN74LS74ADR	SOIC	D	14	2500	346.0	346.0	33.0
SN74LS74ANSR	SO	NS	14	2000	346.0	346.0	33.0
SN74S74NSR	SO	NS	14	2000	346.0	346.0	33.0

DB (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN

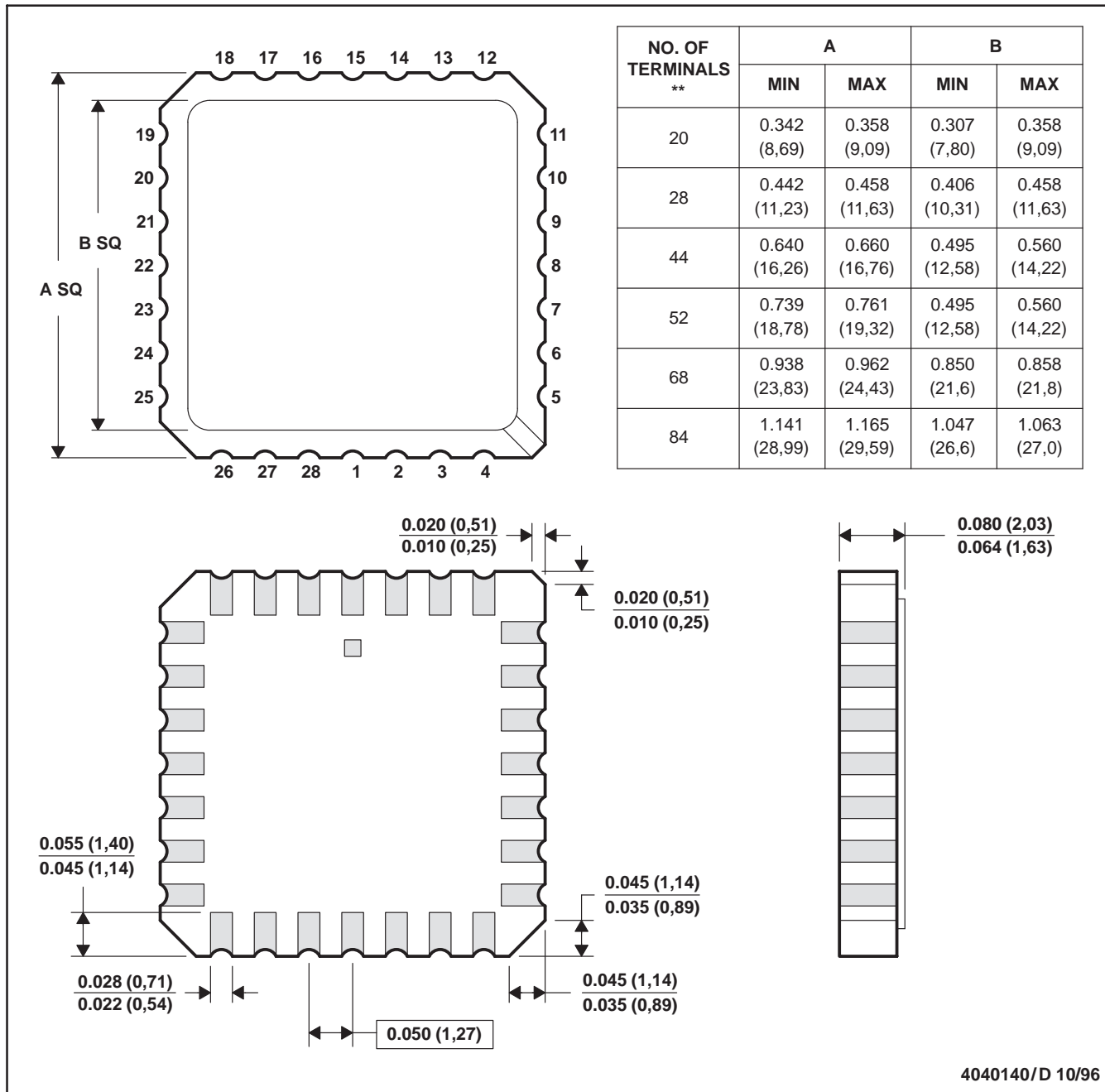


- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



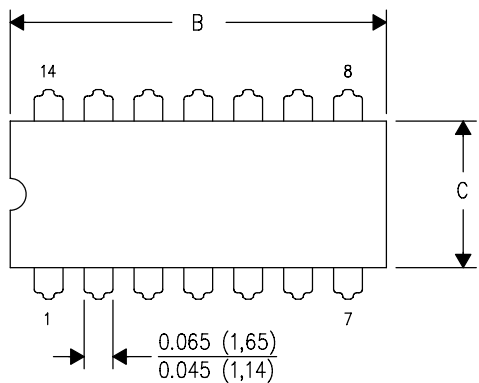
4040140/D 10/96

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a metal lid.
  - D. The terminals are gold plated.
  - E. Falls within JEDEC MS-004

J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



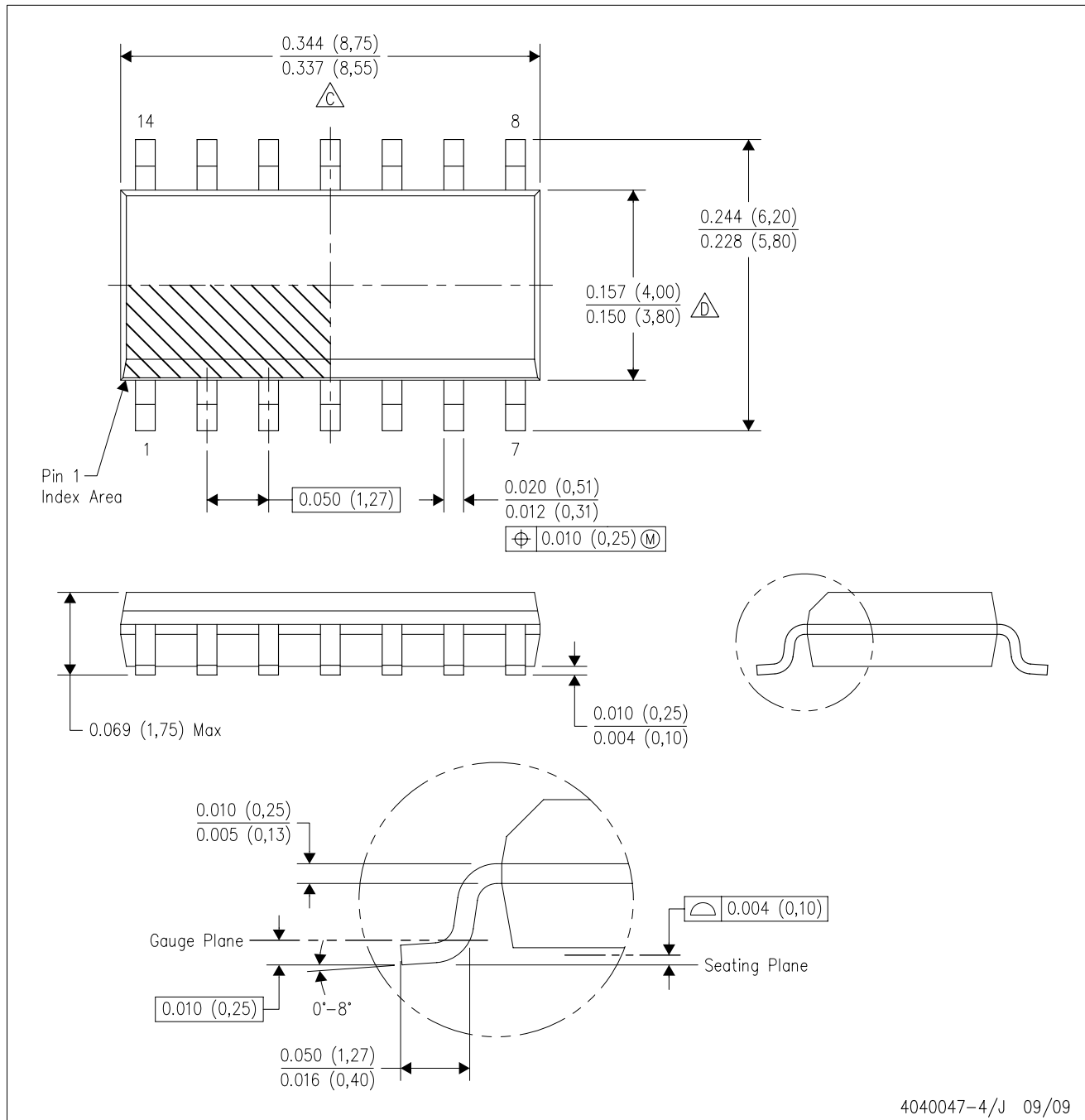
4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.



D (R-PDSO-G14)

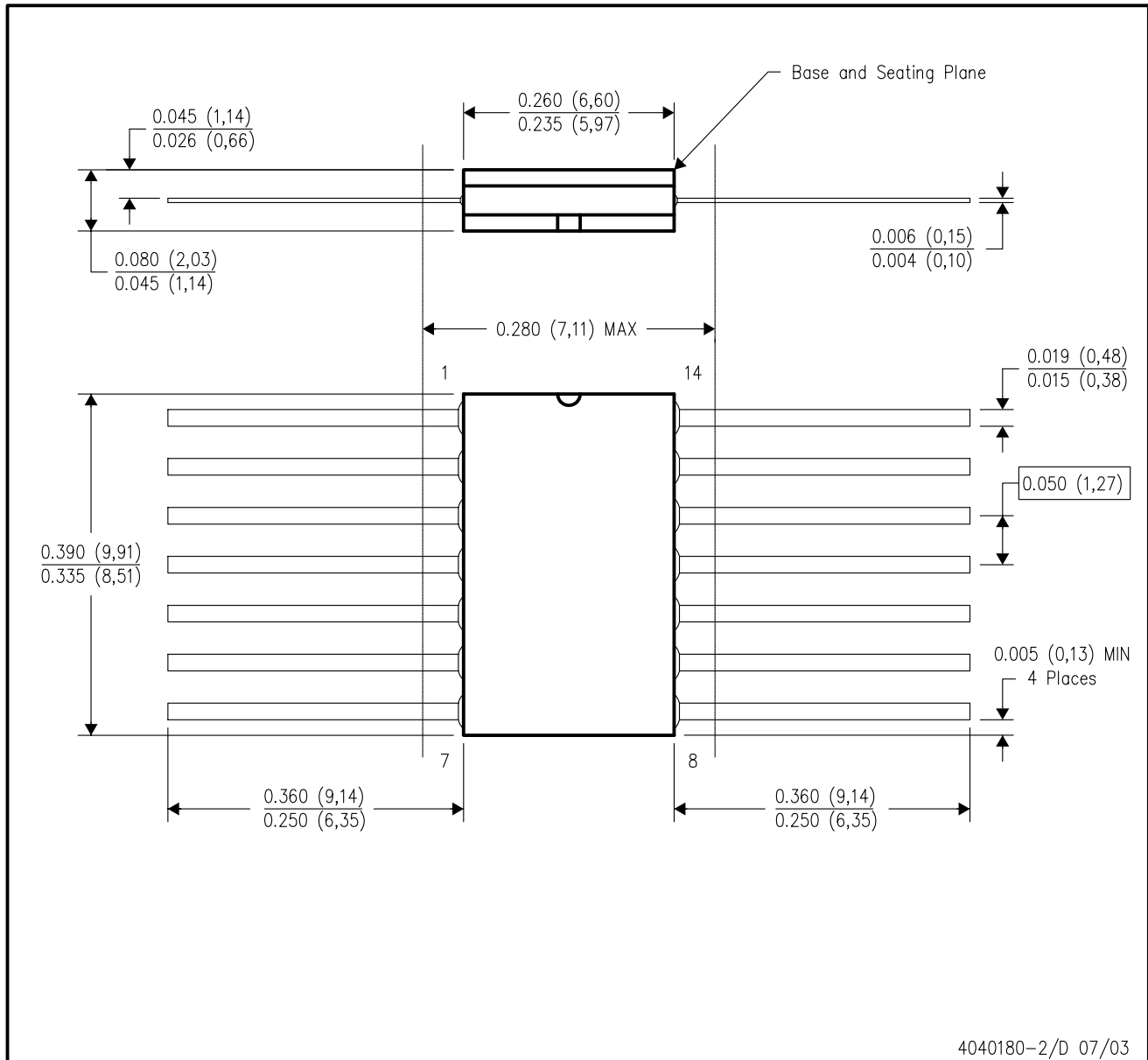
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - $\triangle C$  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
  - $\triangle D$  Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
  - E. Reference JEDEC MS-012 variation AB.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
JM38510/00205BCA	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
JM38510/00205BDA	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI
JM38510/00205BDA	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI
JM38510/07101BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/07101BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/07101BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/07101BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30102B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/30102B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/30102BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/30102BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/30102BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30102BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30102SCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/30102SCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/30102SDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30102SDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SN5474J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN5474J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN54LS74AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54LS74AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54S74J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54S74J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN7474DR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN7474DR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN7474N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7474N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7474N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7474N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS74AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ADBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ADBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ADBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ADBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ADBRG4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ADBRG4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
						no Sb/Br)		
SN74LS74ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74AJ	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74LS74AJ	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74LS74AN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS74AN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS74AN3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS74AN3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS74ANE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS74ANE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS74ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ANSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS74ANSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S74D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S74D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S74DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S74DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S74DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74S74DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S74N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S74N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S74N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74S74N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74S74NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S74NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S74NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S74NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S74NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S74NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S74NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S74NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ5474J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SNJ5474J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SNJ5474W	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI
SNJ5474W	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI
SNJ54LS74AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS74AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS74AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS74AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS74AW	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS74AW	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54S74FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54S74FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54S74J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54S74J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54S74W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54S74W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

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(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS74ADBR	SSOP	DB	14	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN74LS74ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS74ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74S74NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1



**TAPE AND REEL BOX DIMENSIONS**

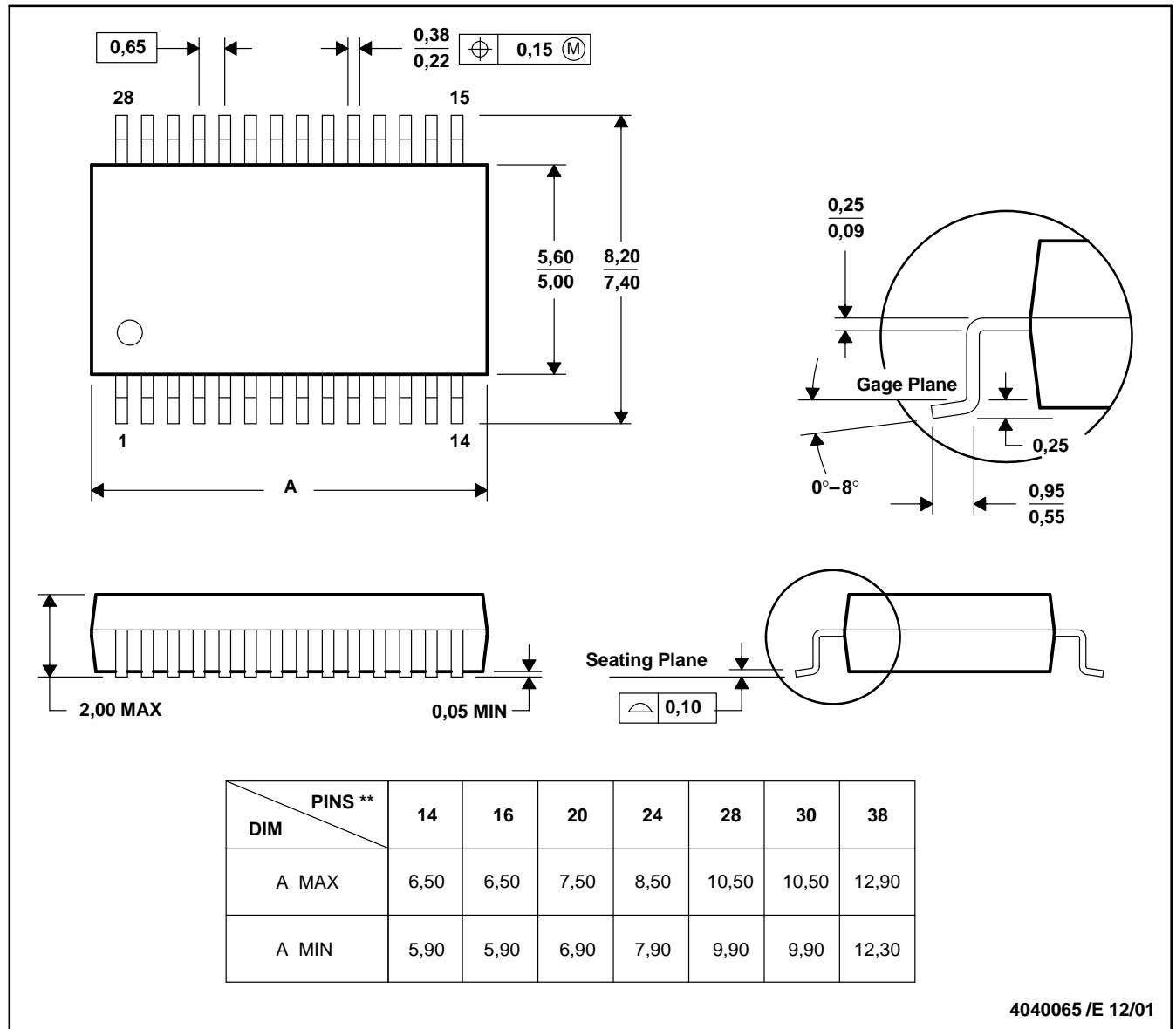

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS74ADBR	SSOP	DB	14	2000	346.0	346.0	33.0
SN74LS74ADR	SOIC	D	14	2500	346.0	346.0	33.0
SN74LS74ANSR	SO	NS	14	2000	346.0	346.0	33.0
SN74S74NSR	SO	NS	14	2000	346.0	346.0	33.0

DB (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN

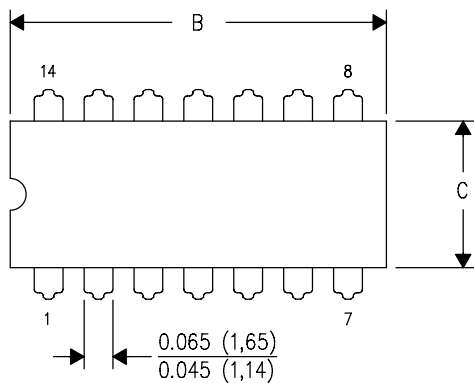


- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a metal lid.
  - D. The terminals are gold plated.
  - E. Falls within JEDEC MS-004

J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

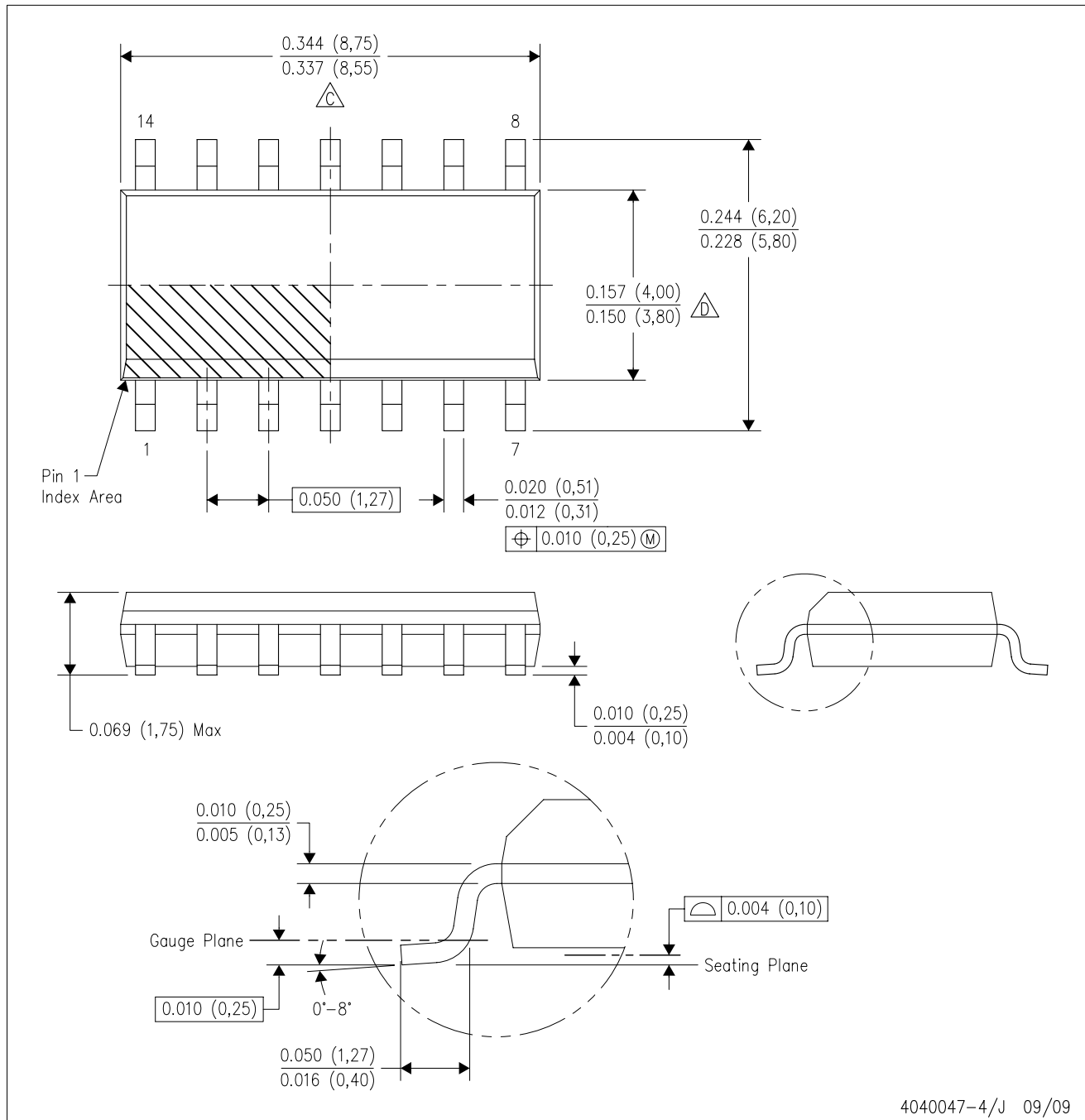


4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

D (R-PDSO-G14)

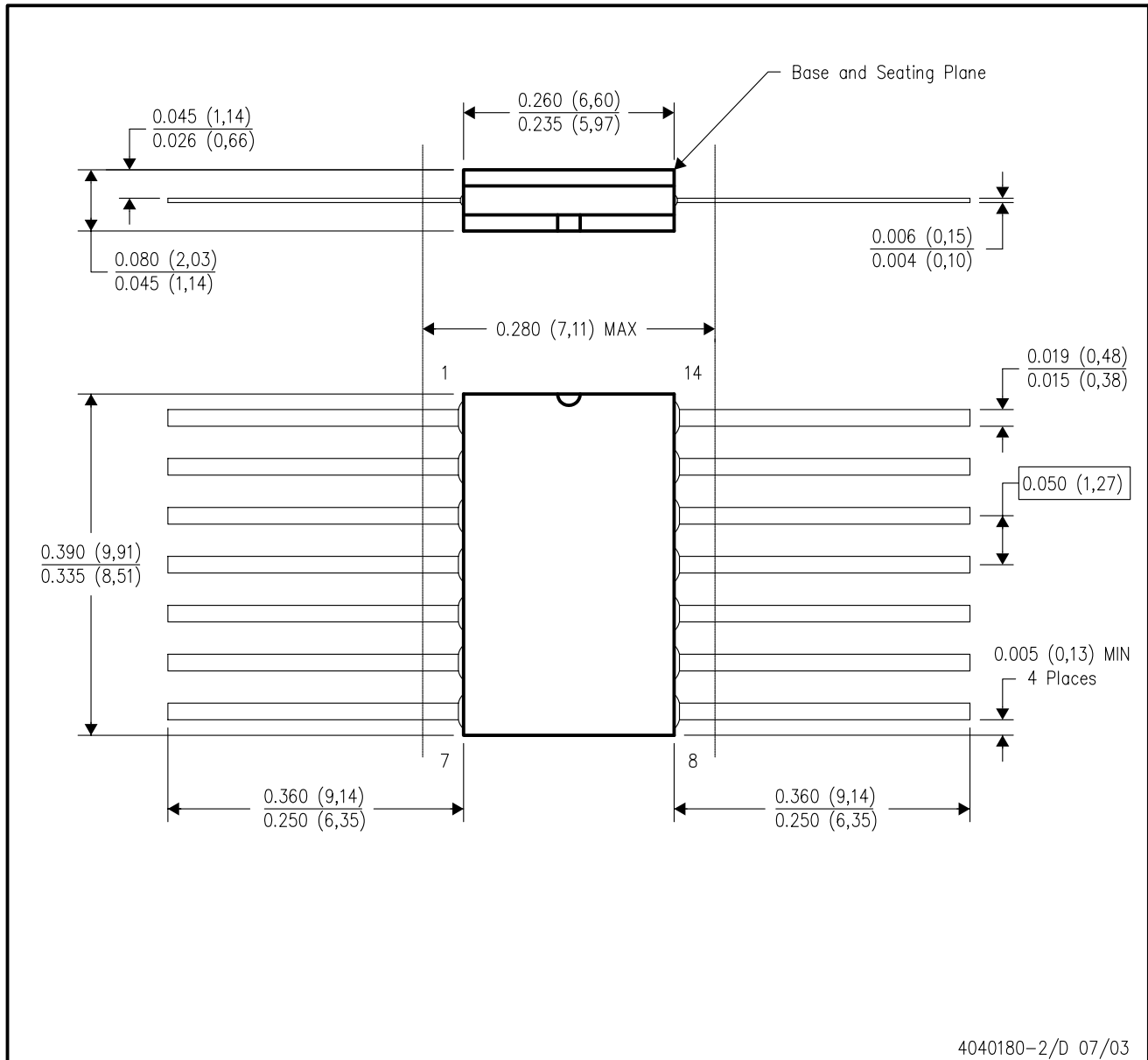
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
  - E. Reference JEDEC MS-012 variation AB.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK

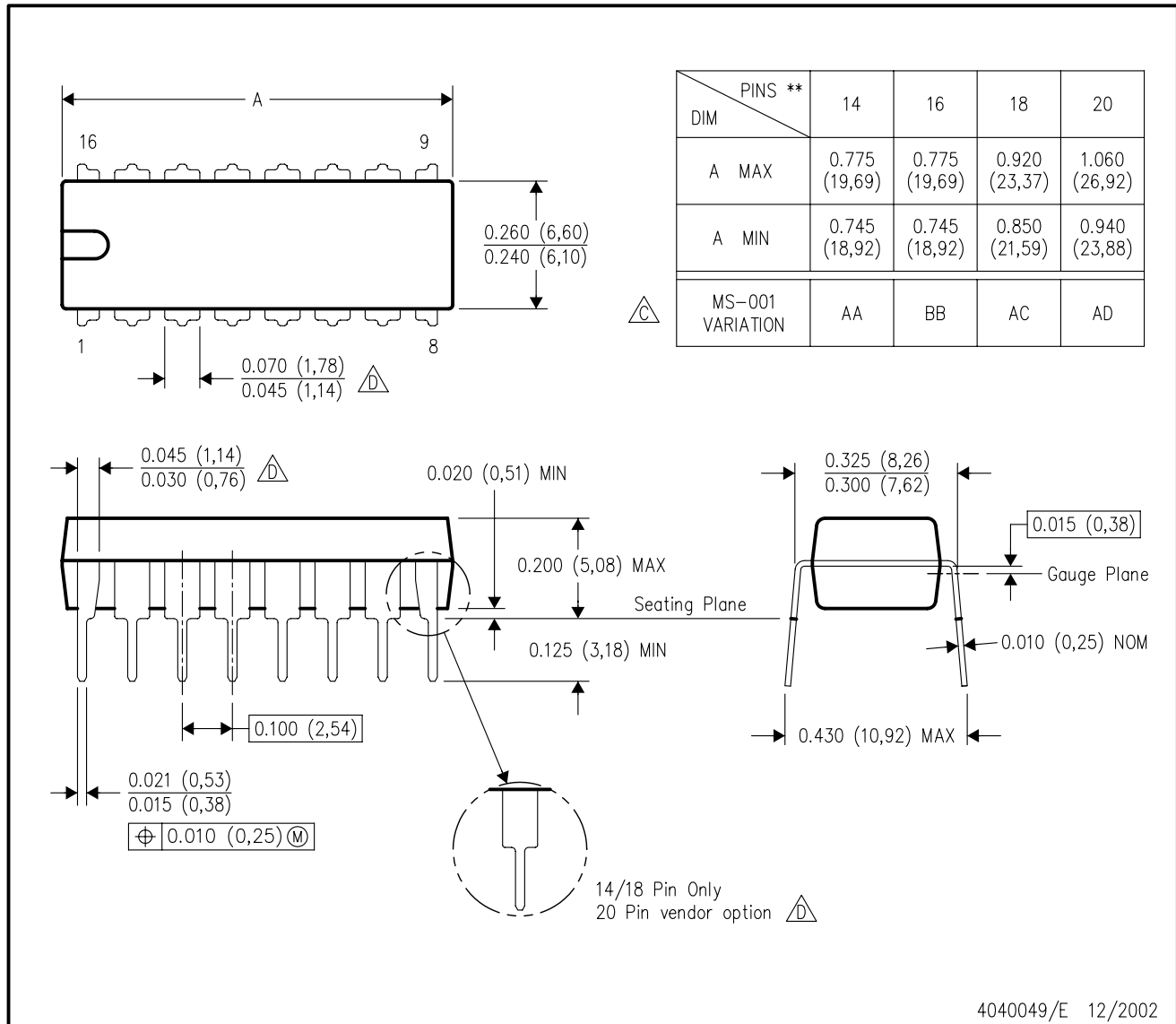


- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.



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Interface	<a href="http://interface.ti.com">interface.ti.com</a>	Energy	<a href="http://www.ti.com/energy">www.ti.com/energy</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>	Industrial	<a href="http://www.ti.com/industrial">www.ti.com/industrial</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>	Medical	<a href="http://www.ti.com/medical">www.ti.com/medical</a>
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